



ABSTRACT OF THE DISCLOSURE

At an IC test system that analyzes a defective place
inside of an IC chip is disclosed. The IC test system
irradiates an ion beam on the surface of the IC device under
test and displays a potential contrast image of wiring
conductors under the surface of the IC device. The present
invention provides an improved method of operability and an
improved image quality and also a capability of specifying a
defective part of the IC under test. A stop pattern setting
means is provided which is able to set a plurality of
patterns to suspend a renewal operation of pattern generation
in a test pattern generator. Whenever this stop pattern
occurs, a pattern renewal action of a test pattern generator
is stopped and an ion beam tester acquires image data. When
the acquisition of image data completes, the test pattern
generator resumes the pattern renewal action. Different test
patterns are alternately applied to the device under test and
the resulting image data is either added or reduced, which
improves an image quality.

YOM-4850
040695